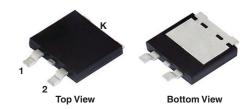
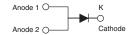


Hyperfast Rectifier, 16 A FRED Pt®

eSMP[®] Series SMPD (TO-263AC)





DESIGN SUPPORT TOOLS AVAILABLE



| PRIMARY CHARACTERISTICS | | | | |
|----------------------------------|-----------------|--|--|--|
| I _{F(AV)} | 16 A | | | |
| V_{R} | 200 V | | | |
| V _F at I _F | 0.75 V | | | |
| t _{rr} | 32 ns | | | |
| T _J max. | 175 °C | | | |
| Package | SMPD (TO-263AC) | | | |
| Circuit configuration | Single | | | |

FEATURES

 Hyperfast recovery time, reduced Q_{rr}, and soft recovery



• 175 °C maximum operating junction temperature

Specified for output and snubber operation

COMPLIANT HALOGEN FREE

- Low forward voltage drop
- · Low leakage current
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Meets JESD 201 class 2 whisker test
- Material categorization: for definitions of compliance please see www.vishav.com/doc?99912

DESCRIPTION / APPLICATIONS

State of the art hyperfast recovery rectifiers specifically designed with optimized performance of forward voltage drop and hyperfast recovery time.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness, and reliability characteristics.

These devices are intended for use in the output rectification stage of SMPS, telecom, DC/DC converters as well as freewheeling diode in low voltage inverters and chopper motor drives.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce power dissipation in the switching element.

| ABSOLUTE MAXIMUM RATINGS | | | | | | |
|-----------------------------------|--------------------|---|--------|-------|--|--|
| PARAMETER | SYMBOL | TEST CONDITIONS | VALUES | UNITS | | |
| Peak repetitive reverse voltage | V_{RRM} | | 200 | V | | |
| Average rectified forward current | I _{F(AV)} | T _{solder pad} = 153 °C | 16 | ۸ | | |
| Non-repetitive peak surge current | I _{FSM} | T _J = 25 °C, 6 ms square pulse | 250 | А | | |

| ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified) | | | | | | | |
|--|-----------------------|---|------|-------|------|----|--|
| PARAMETER | SYMBOL | SYMBOL TEST CONDITIONS MIN. TYP. MAX. | | UNITS | | | |
| Breakdown voltage, blocking voltage | V_{BR} , V_{R} | I _R = 100 μA | 200 | 1 | - | | |
| Forward valtage | I _F = 16 A | - | 0.91 | 1.0 | V | | |
| Forward voltage V _F | | I _F = 16 A, T _J = 150 °C | - | 0.75 | 0.84 | | |
| Develope legister comment | | V _R = V _R rated | - | = | 15 | | |
| Reverse leakage current I _R | I _R | $T_J = 150 ^{\circ}\text{C}, V_R = V_R \text{rated}$ | - | 20 | 500 | μΑ | |
| Junction capacitance | C _T | V _R = 200 V | - | 60 | - | pF | |



| DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified) | | | | | | | |
|---|-------------------------|--|---|------|------|------|-------|
| PARAMETER | SYMBOL | TEST CONDITIONS | | MIN. | TYP. | MAX. | UNITS |
| | | $I_F = 1 \text{ A}, dI_F/dt = 50 \text{ A}$ | Vμs, V _R = 30 V | - | 32 | - | |
| Reverse recovery time | | I _F = 0.5 A, I _R = 1 A, I _{rr} = 0.25 A | | - | - | 32 | no |
| neverse recovery time | t _{rr} | T _J = 25 °C | I _F = 16 A, dI _F /dt = 200 A/μs, V _R = 160 V | - | 26 | - | ns |
| | | T _J = 125 °C | | - | 40 | - | |
| Peak recovery current | | T _J = 25 °C | | - | 2.8 | - | Α |
| | I _{RRM} | T _J = 125 °C | | - | 6 | - | _ A |
| Reverse recovery charge Q _{rr} | 0 | T _J = 25 °C | | - | 37 | - | nC |
| | T _J = 125 °C | | - | 125 | - | 110 | |

| THERMAL - MECHANICAL SPECIFICATIONS | | | | | | |
|--|-----------------------------------|----------------------------|------|------|------|-------|
| PARAMETER | SYMBOL | TEST CONDITIONS | MIN. | TYP. | MAX. | UNITS |
| Maximum junction and storage temperature range | T _J , T _{Stg} | | -55 | - | +175 | °C |
| Thermal resistance, junction to solder pad | R _{thJ-Sp} | | - | 1.1 | 1.4 | °C/W |
| Approximate weight | | | | 0.55 | | g |
| Approximate weight | | | | 0.02 | | oz. |
| Marking device | | Case style SMPD (TO-263AC) | | 16EI | DH02 | |

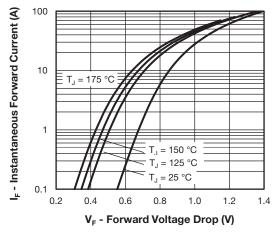


Fig. 1 - Typical Forward Voltage Drop Characteristics

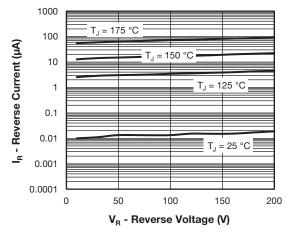


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

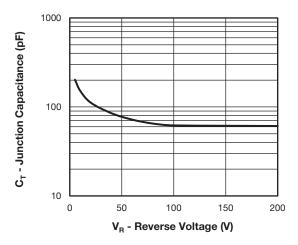


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

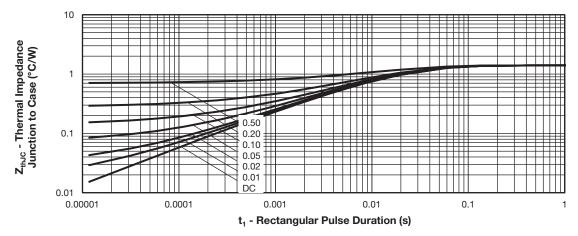


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

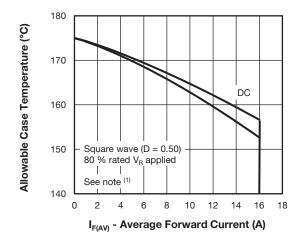


Fig. 5 - Maximum Allowable Case Temperature vs.
Average Forward Current

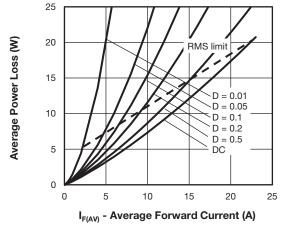


Fig. 6 - Forward Power Loss Characteristics

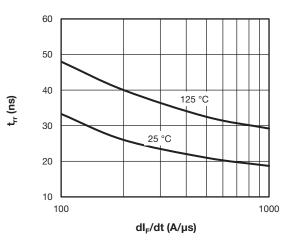
Note

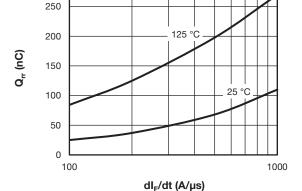
⁽¹⁾ Formula used: T_C = T_J - (Pd + Pd_{REV}) x R_{thJC}; Pd = forward power loss = I_{F(AV)} x V_{FM} at (I_{F(AV)}/D) (see fig. 5); Pd_{REV} = inverse power loss = V_{R1} x I_R (1 - D); I_R at V_{R1} = rated V_R



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Vishay Semiconductors

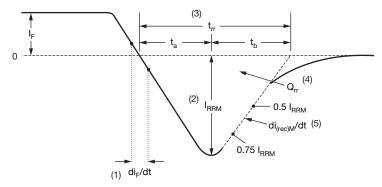




300

Fig. 7 - Typical Reverse Recovery Time vs. dl_F/dt

Fig. 8 - Typical Stored Charge vs. dl_F/dt



- (1) di_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) t_{rr} reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through 0.75 I_{RRM} and 0.50 I_{RRM} extrapolated to zero current.
- (4) \mathbf{Q}_{rr} area under curve defined by \mathbf{t}_{rr} and \mathbf{I}_{RRM}

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

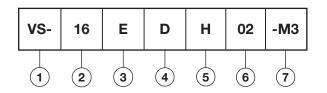
(5) $di_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

Fig. 9 - Reverse Recovery Waveform and Definitions



ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

Current rating (16 A)

3 - Circuit configuration:

E = single die

- D = SMPD package

5 - Process type,

H = hyperfast recovery

6 - Voltage code (02 = 200 V)

7 - -M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

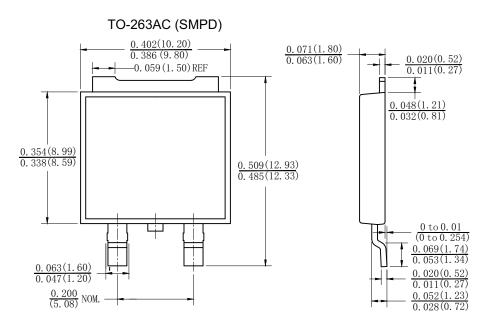
| ORDERING INFORMATION (Example) | | | | | |
|--|------|------|------------------------------------|--|--|
| PREFERRED P/N QUANTITY PER REEL MINIMUM ORDER QUANTITY PACKAGING DESCRIPTION | | | | | |
| VS-16EDH02-M3/I | 2000 | 2000 | 13" diameter plastic tape and reel | | |

| LINKS TO RELATED DOCUMENTS | | | | |
|--|--------------------------|--|--|--|
| Dimensions <u>www.vishay.com/doc?95604</u> | | | | |
| Part marking information | www.vishay.com/doc?95566 | | | |
| Packaging information | www.vishay.com/doc?88869 | | | |

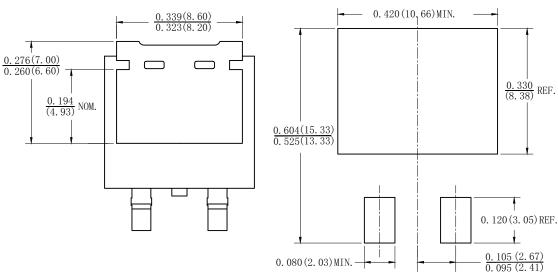


TO-263AC (SMPD)

DIMENSIONS in inches (millimeters)



Mounting Pad Layout





Legal Disclaimer Notice

Vishay

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